502280960 03/21/2013

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|------------------|----------------|
| Venkat Dukkipati | 03/04/2013 |
| Larry Rhodes | 03/01/2013 |

RECEIVING PARTY DATA

| Name: | Promerus, LLC |
|-----------------|-----------------------|
| Street Address: | 9921 Brecksville Road |
| City: | Brecksville |
| State/Country: | ОНЮ |
| Postal Code: | 44141 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 13749754 |

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 440-922-0300

Email: kim.shaver@promerus.com

Correspondent Name: Promerus, LLC
Address Line 1: 9921 Brecksville Road
Address Line 4: Brecksville, OHIO 44141

ATTORNEY DOCKET NUMBER: TWB211-0001A US

Balaram Gupta

Total Attachments: 2

NAME OF SUBMITTER:

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PATENT REEL: 030058 FRAME: 0696 \$40.00 13749<u>7</u>

502280960

ASSIGNMENT

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in

| | ROOM TEMPERATURE DEBONDING COMPOSITION, METHOD AND STACK |
|-----|--|
| | (Invention Title) |
| | for which I have this day executed an application for a United States Patent (hereinafter "said application"). |
| AND | D/OR |
| X | for which an application for a United States Patent was filed on 01/25/2013 (mm/dd/yyyy) and bears Application Number 13/749,754 (hereinafter "said application"). |
| AND | D/OR |
| | for which an international patent application was filed under the Patent Cooperation Treaty on(mm/dd/yyyy), bearing Application No (hereinafter "said application"). |

AND, WHEREAS, Promerus LLC, a corporation of the State of Delaware, having a place of business at 9921 Brecksville Road, Building R, Brecksville, OH 44141, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs, executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

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| 1. FULL NAME OF ASSIGNOR: | RESIDENCE: |
|--|-----------------------------------|
| Venkat Dukkipati | Copley, Ohio 44321 |
| EXECUTED this day of Massch | -, 2013 O- Vonkel-Rom SIGNATURE |
| | |
| 2. FULL NAME OF ASSIGNOR: | RESIDENCE: |
| Larry Rhodes | Silver Lake, Ohio 44224 |
| EXECUTED thisday ofMach | ,2013 Jan Jane |
| 3. FULL NAME OF ASSIGNOR: | RESIDENCE: |
| annual control of the | |
| EXECUTED thisday of | 2013 |
| | SIGNATURE |

Checked Box indicates <u>1</u> additional page(s) for inventor signatures.

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